

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Yoshihiro Zaitso	07/05/2011
Kazuaki Hokoda	07/10/2011
Tatsuya Umeyama	07/11/2011
Shintaro Hirabayashi	07/11/2011
RECEIVING PARTY DATA	
Name:	Stanley Electric Co., Ltd.
Street Address:	2-9-13 Nakameguro, Meguro-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	153-8636
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13153375
CORRESPONDENCE DATA	
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NAME OF SUBMITTER:	David J. Kenealy
Total Attachments: 2 source=Executed_Assignemnt_for_G11-001US#page1.tif source=Executed_Assignemnt_for_G11-001US#page2.tif	

OP \$40.00 13153375

ASSIGNMENT

WHEREAS WE, the below named inventors, [hereinafter referred to as Assignors], have made an invention entitled:

METHOD FOR MANUFACTURING RESIN MOLDING AND LASER BEAM IRRADIATION APPARATUS

for which WE executed an application for United States Letters Patent concurrently herewith and for which WE filed Japanese Patent Application Nos. 2010-127640 on June 3, 2010 and 2010-179349 on August 10, 2010; and

WHEREAS STANLEY ELECTRIC CO., LTD., a corporation of Japan, whose post office address is 2-9-13 Nakameguro, Meguro-ku, Tokyo 153-8636 Japan (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application of United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for and in consideration of the sum of One Dollar (\$1.00) in hand paid and other good and valuable consideration the receipt of which from Assignee is hereby acknowledged, WE, as assignors, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such applications, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent of this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, WE HEREBY covenant that WE have the full right to convey the interest assigned by this Assignment, and WE have not executed and will not execute any agreement in conflict with this Assignment;

AND, WE HEREBY further covenant and agree that WE will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to US respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns;

AND, WE HEREBY authorize and request the attorneys WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. 13/153,375, filed June 3, 2011) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I have hereunto set my hand.

<u>Full Name of First Assignor</u> Yoshihiro ZAITSU	<u>Assignor's Signature</u> <i>Yoshihiro ZaitSU</i>	<u>Date</u> July 5, 2011
<u>Address:</u> c/o Stanley Electric Co., Ltd. 2-9-13, Nakameguro, Meguro-ku, Tokyo 153-8636 JAPAN		<u>Citizenship</u> Japan
Names of additional inventors attached <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No		

KENEALY VAIDYA LLP

<u>Full Name of Second Assignor</u> Kazuaki HOKODA	<u>Assignor's Signature</u> <i>Kazuaki Hokoda</i>	<u>Date</u> <i>July 10, 2011</i>
<u>Address:</u> c/o Stanley Electric Co., Ltd. 2-9-13, Nakameguro, Meguro-ku, Tokyo 153-8636 JAPAN		<u>Citizenship:</u> Japan
<u>Full Name of Third Assignor</u> Tatsuya UMEYAMA	<u>Assignor's Signature</u> <i>Tatsuya Umeyama</i>	<u>Date</u> <i>July 11, 2011</i>
<u>Address:</u> c/o Stanley Electric Co., Ltd. 2-9-13, Nakameguro, Meguro-ku, Tokyo 153-8636 JAPAN		<u>Citizenship:</u> Japan
<u>Full Name of Fourth Assignor</u> Shintaro HIRABAYASHI	<u>Assignor's Signature</u> <i>Shintaro Hirabayashi</i>	<u>Date</u> <i>July 11, 2011</i>
<u>Address:</u> c/o Stanley Electric Co., Ltd. 2-9-13, Nakameguro, Meguro-ku, Tokyo 153-8636 JAPAN		<u>Citizenship:</u> Japan
<p style="text-align: center;">Names of additional inventors attached <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>		

KENEALY VAIDYA LLP

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